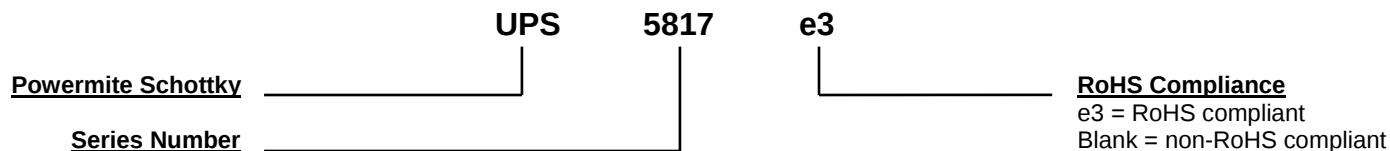


MECHANICAL and PACKAGING

- CASE: Molded epoxy package meets UL94V-0.
- TERMINALS: Copper with annealed matte-tin plating for RoHS compliance. Solderable per MIL-STD-750 method 2026. (Consult factory for tin-lead plating).
- MARKING: Body marked with "S17" or "S19".
- POLARITY: Cathode designated by Tab 1 (bottom).
- TAPE & REEL option: Packaging per EIA-481-B with 8 mm tape. Consult factory for quantities.
- WEIGHT: Approximately 0.016 grams.
- See [Package Dimensions](#) on last page.

PART NOMENCLATURE

ELECTRICAL CHARACTERISTICS

RATING (Conditions)	SYMBOL	VALUE		UNIT
		UPS5817	UPS5819	
Maximum Instantaneous Forward Voltage ⁽²⁾ ($I_F = 1.0 \text{ A}$, $T_J = +25 \text{ }^\circ\text{C}$)	V_F	0.45	0.55	Volts
Maximum Instantaneous Reverse Current ⁽²⁾ ($V_R = 20 \text{ V}$, $T_J = +25 \text{ }^\circ\text{C}$)	I_{RM}	1.0	1.0	mA
Typical Junction Capacitance ($V_R = 5\text{V}$, $f = 1 \text{ MHz}$)	C_J	105	60	pF

Notes: 2. Measured with a test pulse of 380 μs to minimize self-heating effect.

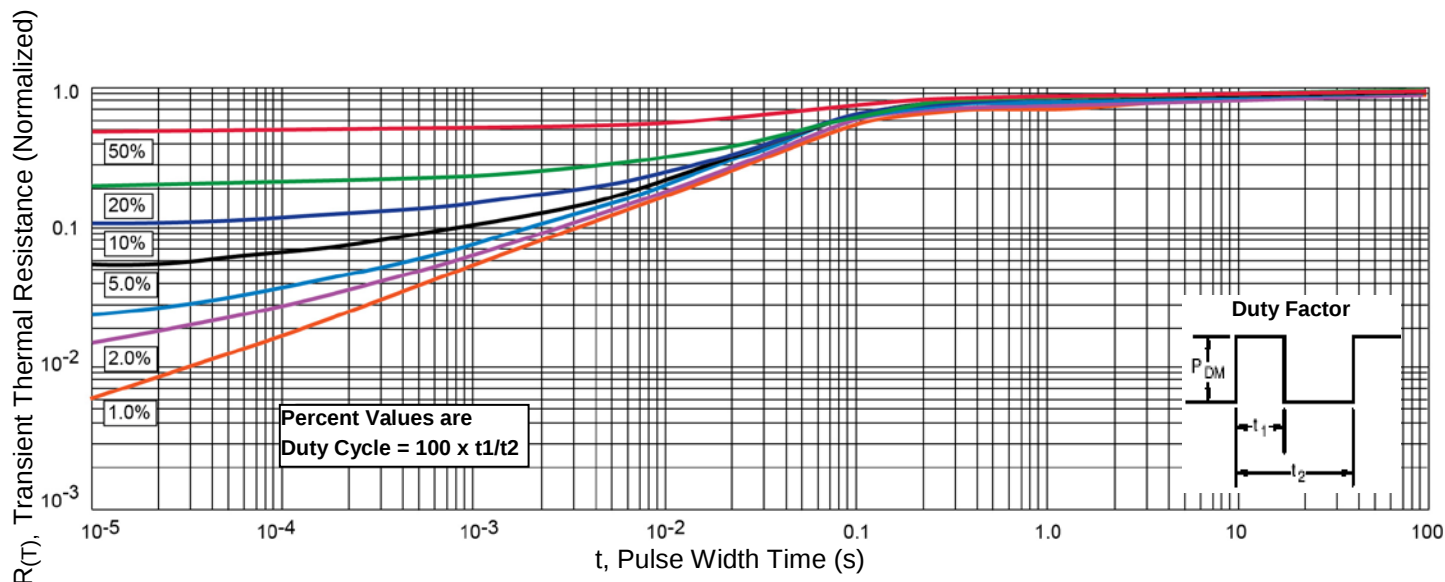
GRAPHS


FIGURE 1
Thermal Impedance Junction to Case

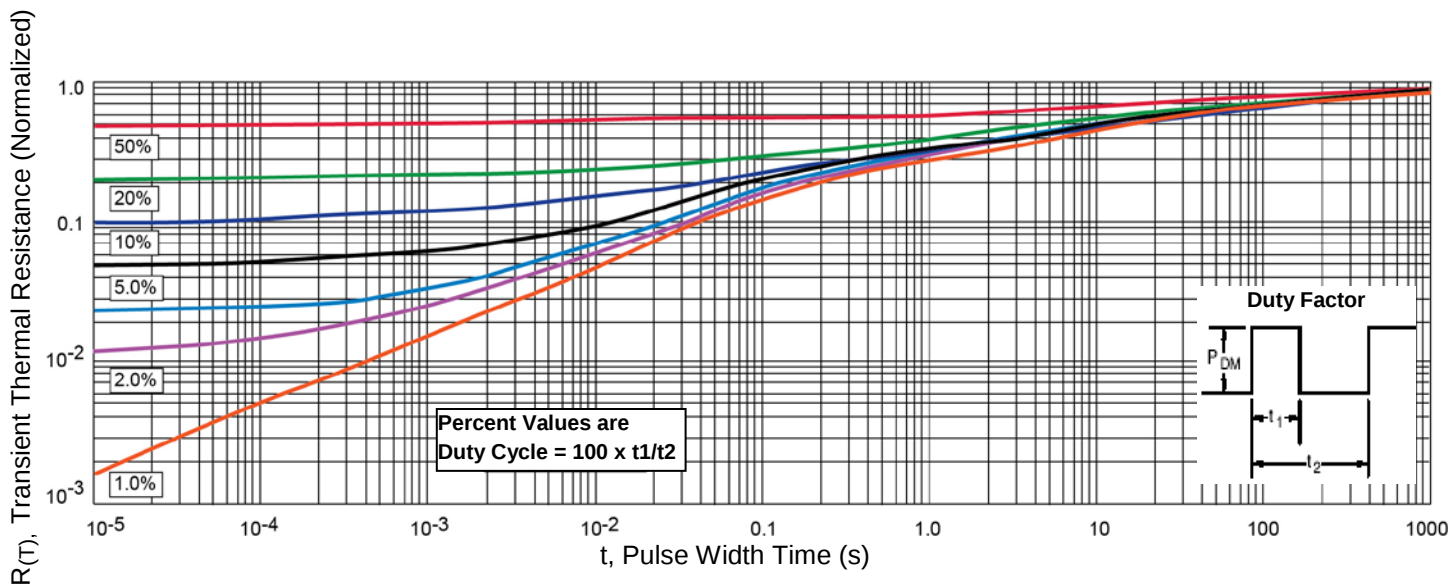
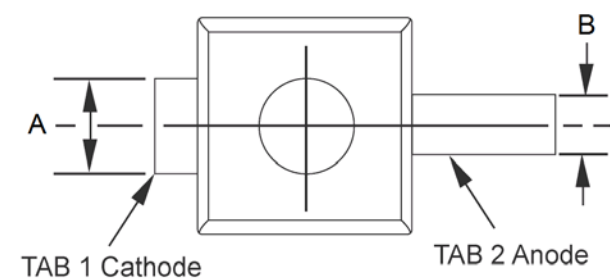
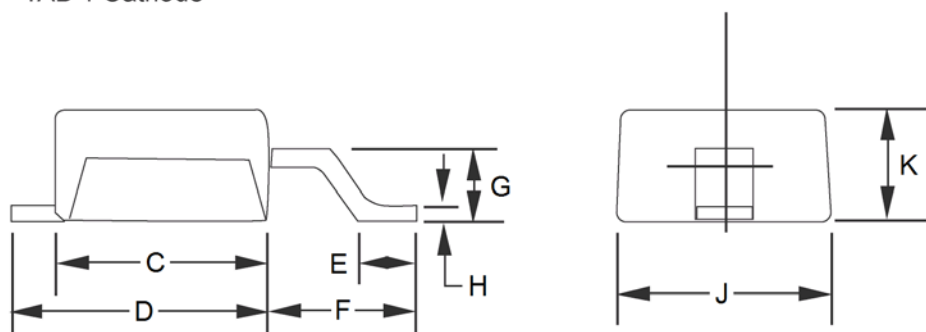
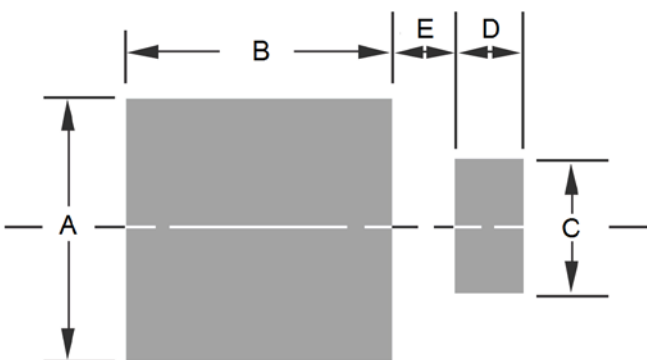


FIGURE 2
Thermal Impedance Junction to Ambient

PACKAGE DIMENSIONS


Ltr	Dimensions			
	Inch		Millimeters	
	Min	Max	Min	Max
A	0.029	0.039	0.73	0.99
B	0.016	0.026	0.40	0.66
C	0.070	0.080	1.77	2.03
D	0.087	0.097	2.21	2.46
E	0.020	0.030	0.50	0.76
F	0.051	0.061	1.29	1.54
G	0.021	0.031	0.53	0.78
H	0.004	0.008	0.10	0.20
J	0.070	0.080	1.77	2.03
K	0.035	0.045	0.89	1.14


PAD LAYOUT


Ltr	Dimensions	
	Inch	Millimeters
A	0.100	2.54
B	0.105	2.67
C	0.050	1.27
D	0.030	0.76
E	0.025	0.64

SCHEMATIC
